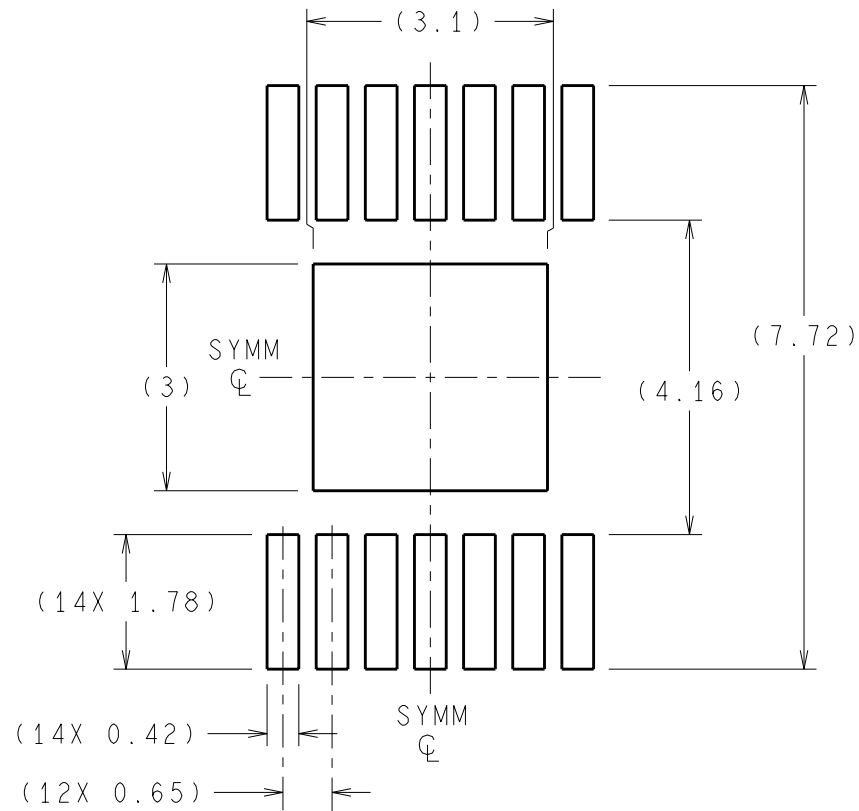
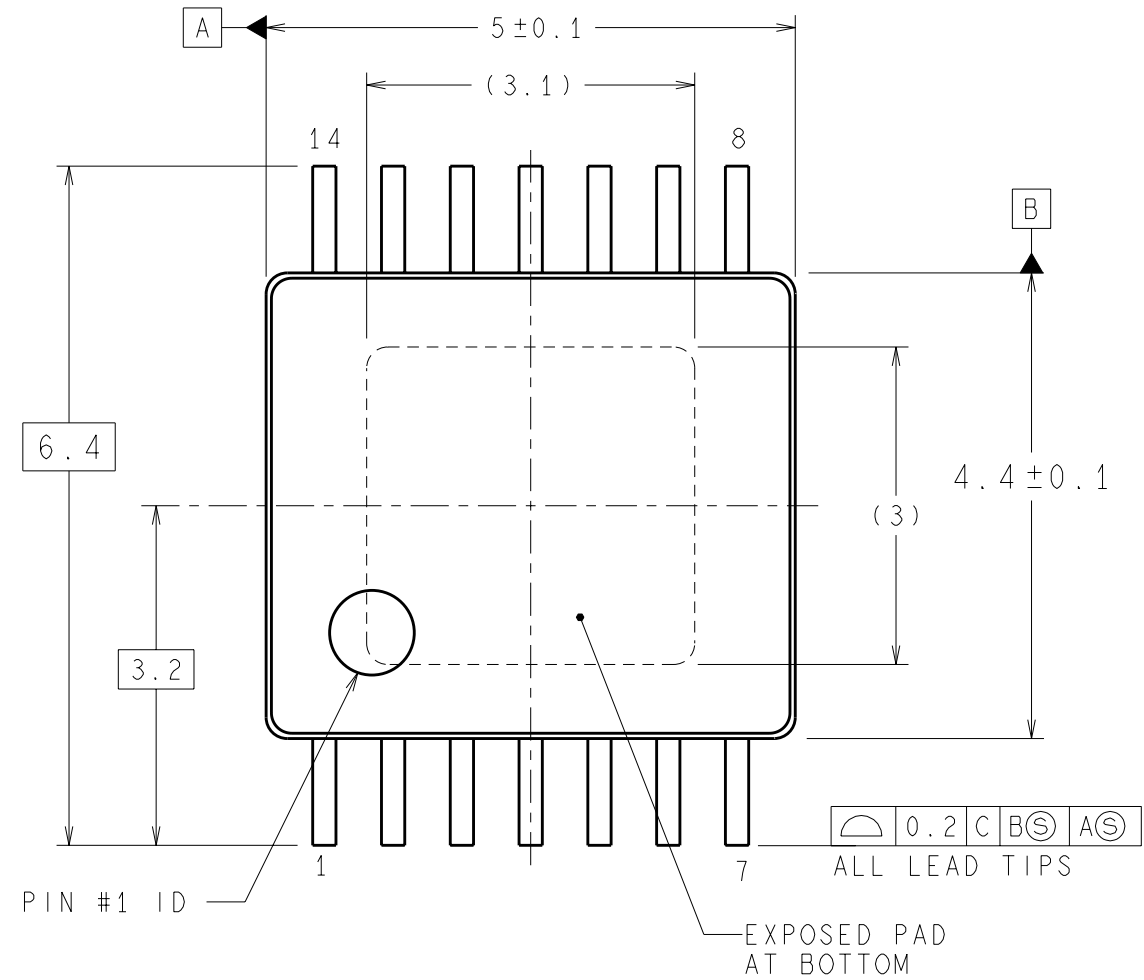
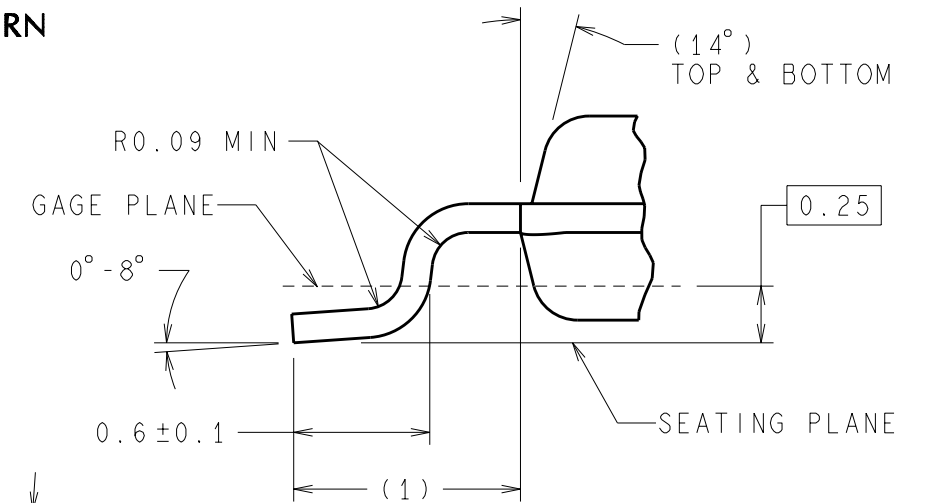


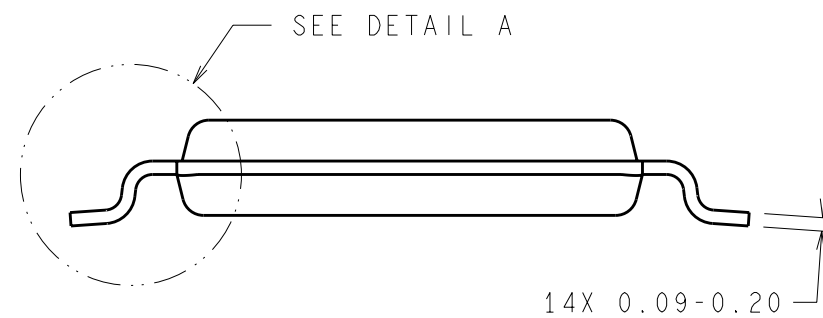
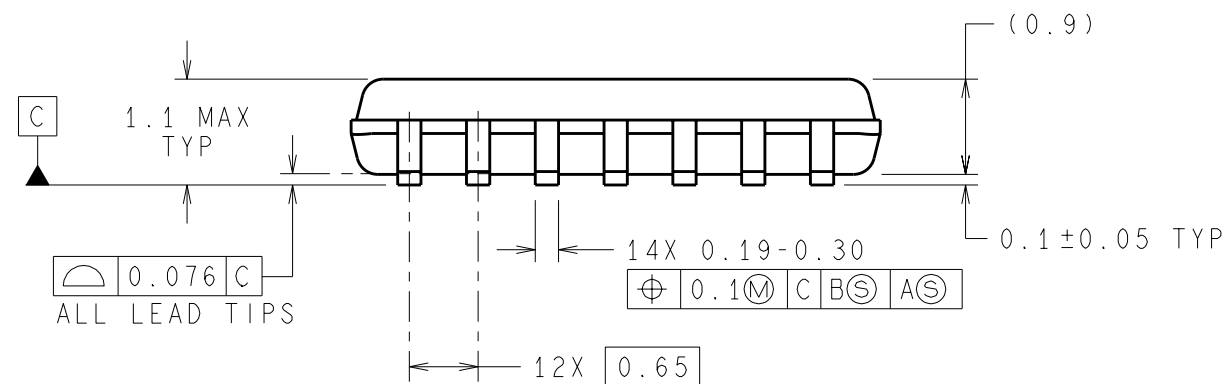
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	944	02/12/2003	TL/RW



RECOMMENDED LAND PATTERN



DETAIL A
TYP, SCALE: 30X



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. REFERENCE JEDEC REGISTRATION MO-153, VARIATION ABT-1.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN T. LEQUANG		02/12/2003	
DFTG. CHK. MARTA SUCHY		02/12/2003	
ENGR. CHK. RANDALL WALBERG		02/12/2003	
MOLDED TSSOP, JEDEC, EXP PAD, 5.0x4.4x0.9mm BODY, 14 LD, 0.65mm PITCH			
PROJECTION 	SCALE NTS	SIZE B	DRAWING NUMBER (SC)MKT-MXA14A
FORMERLY: N/A			REV A SHEET 1 of 1